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Details	
Product Status	Active
Number of LABs/CLBs	9360
Number of Logic Elements/Cells	149760
Total RAM Bits	6635520
Number of I/O	393
Number of Gates	-
Voltage - Supply	1.16V ~ 1.24V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4cgx150df27c7

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Cyclone IV E industrial devices I7 are offered with extended operating temperature range.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Cyclone IV devices. The values are based on experiments conducted with the device and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied at these conditions. Table 1–1 lists the absolute maximum ratings for Cyclone IV devices.



Conditions beyond those listed in Table 1–1 cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time have adverse effects on the device.

Table 1–1. Absolute Maximum Ratings for Cyclone IV Devices (1)

Symbol	Parameter	Min	Max	Unit
V _{CCINT}	Core voltage, PCI Express® (PCIe®) hard IP block, and transceiver physical coding sublayer (PCS) power supply	-0.5	1.8	V
V _{CCA}	Phase-locked loop (PLL) analog power supply	-0.5	3.75	V
V _{CCD_PLL}	PLL digital power supply	-0.5	1.8	V
V _{CCIO}	I/O banks power supply	-0.5	3.75	V
V _{CC_CLKIN}	Differential clock input pins power supply	-0.5	4.5	V
V _{CCH_GXB}	Transceiver output buffer power supply	-0.5	3.75	V
V _{CCA_GXB}	Transceiver physical medium attachment (PMA) and auxiliary power supply	-0.5	3.75	V
V _{CCL_GXB}	Transceiver PMA and auxiliary power supply	-0.5	1.8	V
VI	DC input voltage	-0.5	4.2	V
I _{OUT}	DC output current, per pin	-25	40	mA
T _{STG}	Storage temperature	-65	150	°C
T _J	Operating junction temperature	-40	125	°C

Note to Table 1-1:

Maximum Allowed Overshoot or Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in Table 1–2 and undershoot to -2.0 V for a magnitude of currents less than 100 mA and for periods shorter than 20 ns. Table 1-2 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage over the lifetime of the device. The maximum allowed overshoot duration is specified as a percentage of high-time over the lifetime of the device.

⁽¹⁾ Supply voltage specifications apply to voltage readings taken at the device pins with respect to ground, not at the power supply.



A DC signal is equivalent to 100% duty cycle. For example, a signal that overshoots to 4.3 V can only be at 4.3 V for 65% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 65/10ths of a year.

Table 1–2. Maximum Allowed Overshoot During Transitions over a 10-Year Time Frame for Cyclone IV Devices

Symbol	Parameter	Condition (V)	Overshoot Duration as % of High Time	Unit
		V _I = 4.20	100	%
		V _I = 4.25	98	%
	V _I = 4.30	65	%	
	40 1	V _I = 4.35	43	%
V _i	AC Input Voltage	V _I = 4.40	29	%
	l	V _I = 4.45	20	%
		V _I = 4.50	13	%
		V _I = 4.55	9	%
		V _I = 4.60	6	%

Figure 1–1 shows the methodology to determine the overshoot duration. The overshoot voltage is shown in red and is present on the input pin of the Cyclone IV device at over 4.3 V but below 4.4 V. From Table 1–2, for an overshoot of 4.3 V, the percentage of high time for the overshoot can be as high as 65% over a 10-year period. Percentage of high time is calculated as ([delta T]/T) \times 100. This 10-year period assumes that the device is always turned on with 100% I/O toggle rate and 50% duty cycle signal. For lower I/O toggle rates and situations in which the device is in an idle state, lifetimes are increased.

Figure 1-1. Cyclone IV Devices Overshoot Duration

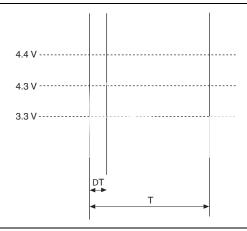


Table 1–3. Recommended Operating Conditions for Cyclone IV E Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I _{Diode}	Magnitude of DC current across PCI-clamp diode when enable	_	_	_	10	mA

Notes to Table 1-3:

- (1) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades.
- (2) V_{CCIO} for all I/O banks must be powered up during device operation. All VCCA pins must be powered to 2.5 V (even when PLLs are not used) and must be powered up and powered down at the same time.
- (3) V_{CC} must rise monotonically.
- (4) V_{CCIO} powers all input buffers.
- (5) The POR time for Standard POR ranges between 50 and 200 ms. Each individual power supply must reach the recommended operating range within 50 ms.
- (6) The POR time for Fast POR ranges between 3 and 9 ms. Each individual power supply must reach the recommended operating range within 3 ms.

Table 1-4. Recommended Operating Conditions for Cyclone IV GX Devices (Part 1 of 2)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{CCINT} (3)	Core voltage, PCIe hard IP block, and transceiver PCS power supply	_	1.16	1.2	1.24	V
V _{CCA} (1), (3)	PLL analog power supply	_	2.375	2.5	2.625	V
V _{CCD_PLL} (2)	PLL digital power supply	_	1.16	1.2	1.24	V
V _{CCIO} (3). (4) 0 1/ 0 1/ 0 1/ 0 1/ 0 1/ 0 1/ 0 1/ 0 1/ 0 1/ 0 D	I/O banks power supply for 3.3-V operation	_	3.135	3.3	3.465	V
	I/O banks power supply for 3.0-V operation	_	2.85	3	3.15	V
	I/O banks power supply for 2.5-V operation	_	2.375	2.5	2.625	V
	I/O banks power supply for 1.8-V operation	_	1.71	1.8	1.89	V
	I/O banks power supply for 1.5-V operation	_	1.425	1.5	1.575	V
	I/O banks power supply for 1.2-V operation	_	1.14	1.2	1.26	V
V _{CC_CLKIN} (3). (4) I/O banks power supply for 1.8-V operation I/O banks power supply for 1.5-V operation I/O banks power supply for 1.2-V operation Differential clock input pins power supply for 3.3-V operation Differential clock input pins power supply for 3.0-V operation Differential clock input pins power supply for 2.5-V operation Differential clock input pins power supply for 2.5-V operation Differential clock input pins power supply for 2.5-V operation		_	3.135	3.3	3.465	V
	_	2.85	3	3.15	V	
V _{CC_CLKIN}		_	2.375	2.5	2.625	V
(3), (5), (6)	Differential clock input pins power supply for 1.8-V operation	_	1.71	1.8	1.89	V
	Differential clock input pins power supply for 1.5-V operation	_	1.425	1.5	1.575	V
	Differential clock input pins power supply for 1.2-V operation	_	1.14	1.2	1.26	V
V_{CCH_GXB}	Transceiver output buffer power supply	_	2.375	2.5	2.625	V

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{CCA_GXB}	Transceiver PMA and auxiliary power supply	_	2.375	2.5	2.625	V
V _{CCL_GXB}	Transceiver PMA and auxiliary power supply	_	1.16	1.2	1.24	V
V _I	DC input voltage	_	-0.5		3.6	V
V ₀	DC output voltage	_	0	_	V _{CCIO}	V
т		For commercial use	0		85	°C
T _J	Operating junction temperature	For industrial use	-40	_	100	°C
t _{RAMP}	Power supply ramp time	Standard power-on reset (POR) (7)	50 μs	_	50 ms	_
10 000		Fast POR (8)	50 μs	_	3 ms	_
I _{Diode}	Magnitude of DC current across PCI-clamp diode when enabled	_	_	ı	10	mA

Notes to Table 1-4:

- (1) All VCCA pins must be powered to 2.5 V (even when PLLs are not used) and must be powered up and powered down at the same time.
- (2) You must connect V_{CCD PLL} to V_{CCINT} through a decoupling capacitor and ferrite bead.
- (3) Power supplies must rise monotonically.
- (4) V_{CCIO} for all I/O banks must be powered up during device operation. Configurations pins are powered up by V_{CCIO} of I/O Banks 3, 8, and 9 where I/O Banks 3 and 9 only support V_{CCIO} of 1.5, 1.8, 2.5, 3.0, and 3.3 V. For fast passive parallel (FPP) configuration mode, the V_{CCIO} level of I/O Bank 8 must be powered up to 1.5, 1.8, 2.5, 3.0, and 3.3 V.
- (5) You must set $V_{\text{CC_CLKIN}}$ to 2.5 V if you use CLKIN as a high-speed serial interface (HSSI) refclk or as a DIFFCLK input.
- (6) The CLKIN pins in I/O Banks 3B and 8B can support single-ended I/O standard when the pins are used to clock left PLLs in non-transceiver applications.
- (7) The POR time for Standard POR ranges between 50 and 200 ms. V_{CCINT}, V_{CCA}, and V_{CCIO} of I/O Banks 3, 8, and 9 must reach the recommended operating range within 50 ms.
- (8) The POR time for Fast POR ranges between 3 and 9 ms. V_{CCINT}, V_{CCA}, and V_{CCIO} of I/O Banks 3, 8, and 9 must reach the recommended operating range within 3 ms.

ESD Performance

This section lists the electrostatic discharge (ESD) voltages using the human body model (HBM) and charged device model (CDM) for Cyclone IV devices general purpose I/Os (GPIOs) and high-speed serial interface (HSSI) I/Os. Table 1–5 lists the ESD for Cyclone IV devices GPIOs and HSSI I/Os.

Table 1-5. ESD for Cyclone IV Devices GPIOs and HSSI I/Os

Symbol	Parameter	Passing Voltage	Unit
V	ESD voltage using the HBM (GPIOs) (1)	± 2000	V
VESDHBM	ESD using the HBM (HSSI I/Os) (2)	± 1000	V
V	ESD using the CDM (GPIOs)	± 500	V
VESDCDM	ESD using the CDM (HSSI I/Os) (2)	± 250	V

Notes to Table 1-5:

- (1) The passing voltage for EP4CGX15 and EP4CGX30 row I/Os is ±1000V.
- (2) This value is applicable only to Cyclone IV GX devices.

DC Characteristics

This section lists the I/O leakage current, pin capacitance, on-chip termination (OCT) tolerance, and bus hold specifications for Cyclone IV devices.

Supply Current

The device supply current requirement is the minimum current drawn from the power supply pins that can be used as a reference for power size planning. Use the Excel-based early power estimator (EPE) to get the supply current estimates for your design because these currents vary greatly with the resources used. Table 1–6 lists the I/O pin leakage current for Cyclone IV devices.

Table 1-6. I/O Pin Leakage Current for Cyclone IV Devices (1), (2)

Symbol	Parameter	Conditions	Device	Min	Тур	Max	Unit
I _I	Input pin leakage current	$V_I = 0 V \text{ to } V_{CCIOMAX}$		-10	_	10	μΑ
I _{OZ}	Tristated I/O pin leakage current	$V_0 = 0 \text{ V to } V_{\text{CCIOMAX}}$		-10	_	10	μΑ

Notes to Table 1-6:

- This value is specified for normal device operation. The value varies during device power-up. This applies for all V_{CCIO} settings (3.3, 3.0, 2.5, 1.8, 1.5, and 1.2 V).
- (2) The 10 μ A I/O leakage current limit is applicable when the internal clamping diode is off. A higher current can be observed when the diode is on.

Bus Hold

The bus hold retains the last valid logic state after the source driving it either enters the high impedance state or is removed. Each I/O pin has an option to enable bus hold in user mode. Bus hold is always disabled in configuration mode.

Table 1–7 lists bus hold specifications for Cyclone IV devices.

Table 1–7. Bus Hold Parameter for Cyclone IV Devices (Part 1 of 2) (1)

							V _{CCIO}	(V)							
Parameter	Condition	1.2		1	.5	1	.8	2	.5	3	.0	3	.3	Unit	
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
Bus hold low, sustaining current	V _{IN} > V _{IL} (maximum)	8	_	12	_	30	_	50	_	70	_	70	_	μА	
Bus hold high, sustaining current	V _{IN} < V _{IL} (minimum)	-8	_	-12	_	-30	_	-50	_	-70	_	-70	_	μА	
Bus hold low, overdrive current	0 V < V _{IN} < V _{CCIO}	_	125	_	175	_	200	_	300	_	500	_	500	μА	
Bus hold high, overdrive current	0 V < V _{IN} < V _{CCIO}	_	-125	_	-175	_	-200	_	-300	_	-500	_	-500	μА	

Table 1–21. Transceiver Specification for Cyclone IV GX Devices (Part 2 of 4)

Symbol/	Oanditions		C6		C7, I7				C8		Unit
Description	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	UIIIL
Receiver			•				•			<u> </u>	
Supported I/O Standards	1.4 V PCML, 1.5 V PCML, 2.5 V PCML, LVPECL, LVDS										
Data rate (F324 and smaller package) (15)	_	600	_	2500	600	_	2500	600	_	2500	Mbps
Data rate (F484 and larger package) (15)	_	600	_	3125	600	_	3125	600	_	2500	Mbps
Absolute V _{MAX} for a receiver pin (3)	_	_	_	1.6	_	_	1.6	_	_	1.6	V
Operational V _{MAX} for a receiver pin	_	_	_	1.5	_	_	1.5	_	_	1.5	V
Absolute V _{MIN} for a receiver pin	_	-0.4	_	_	-0.4	_	_	-0.4	_	_	V
Peak-to-peak differential input voltage V _{ID} (diff p-p)	V _{ICM} = 0.82 V setting, Data Rate = 600 Mbps to 3.125 Gbps	0.1	_	2.7	0.1	_	2.7	0.1	_	2.7	V
V _{ICM}	V _{ICM} = 0.82 V setting	_	820 ± 10%	_	_	820 ± 10%	_	_	820 ± 10%	_	mV
Differential on-chip	100–Ω setting	_	100	_	_	100	_	_	100	_	Ω
termination resistors	150– Ω setting	_	150	_	_	150	_	_	150	_	Ω
Differential and common mode return loss	PIPE, Serial Rapid I/O SR, SATA, CPRI LV, SDI, XAUI					Compliant	i				_
Programmable ppm detector ⁽⁴⁾	_				± 62.5	, 100, 125 250, 300	5, 200,				ppm
Clock data recovery (CDR) ppm tolerance (without spread-spectrum clocking enabled)	_		_	±300 (5), ±350 (6), (7)		_	±300 (5), ±350 (6), (7)	_	_	±300 (5), ±350 (6), (7)	ppm
CDR ppm tolerance (with synchronous spread-spectrum clocking enabled) (8)	_	_	_	350 to -5350 (7), (9)	_	_	350 to -5350 (7), (9)	_	_	350 to -5350 (7), (9)	ppm
Run length	_		80	_	_	80	_		80		UI
	No Equalization	_	_	1.5	_	_	1.5	_	_	1.5	dB
Programmable	Medium Low	_	_	4.5	_	_	4.5		_	4.5	dB
equalization	Medium High	_	_	5.5	_	_	5.5		_	5.5	dB
	High	_	_	7	_	_	7	_		7	dB

Table 1–21. Transceiver Specification for Cyclone IV GX Devices (Part 3 of 4)

Symbol/	0 1111		C6			C7, I7					
Description	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Signal detect/loss threshold	PIPE mode	65	_	175	65	_	175	65	_	175	mV
t _{LTR} (10)	_	_	_	75	_	_	75	_	_	75	μs
t _{LTR-LTD_Manual} (11)	_	15	_	_	15	_	_	15	_	_	μs
t _{LTD} (12)	_	0	100	4000	0	100	4000	0	100	4000	ns
t _{LTD_Manual} (13)	_		_	4000	_		4000	_		4000	ns
t _{LTD_Auto} (14)	_		_	4000	_		4000	_		4000	ns
Receiver buffer and CDR offset cancellation time (per channel)	_		_	17000	_	_	17000	_	_	17000	recon fig_c lk cycles
	DC Gain Setting = 0	_	0	_	_	0	_	_	0	_	dB
Programmable DC gain	DC Gain Setting = 1	_	3	_	_	3	_	_	3	_	dB
	DC Gain Setting = 2	_	6	_	_	6	_	_	6	_	dB
Transmitter											
Supported I/O Standards	1.5 V PCML										
Data rate (F324 and smaller package)	_	600	_	2500	600	_	2500	600	_	2500	Mbps
Data rate (F484 and larger package)	_	600	_	3125	600	_	3125	600	_	2500	Mbps
V _{OCM}	0.65 V setting	_	650	_	_	650	_	_	650	_	mV
Differential on-chip	100–Ω setting	_	100	_	_	100	_	_	100	_	Ω
termination resistors	150– Ω setting	_	150	_	_	150	_	_	150	_	Ω
Differential and common mode return loss	PIPE, CPRI LV, Serial Rapid I/O SR, SDI, XAUI, SATA		Compliant								_
Rise time	_	50	_	200	50	_	200	50	_	200	ps
Fall time	_	50	_	200	50	_	200	50	_	200	ps
Intra-differential pair skew	_	_	_	15	_	_	15	_	_	15	ps
Intra-transceiver block skew	_	_	_	120	_	_	120	_	_	120	ps

Table 1–21. Transceiver Specification for Cyclone IV GX Devices (Part 4 of 4)

Symbol/	Conditions		C6			C7, I7			C8		Unit
Description	Collultions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	UIIIL
PLD-Transceiver Inte	rface										
Interface speed (F324 and smaller package)	_	25	_	125	25	_	125	25	_	125	MHz
Interface speed (F484 and larger package)	_	25	_	156.25	25	_	156.25	25	_	156.25	MHz
Digital reset pulse width	_	Minimum is 2 parallel clock cycles									

Notes to Table 1-21:

- (1) This specification is valid for transmitter output jitter specification with a maximum total jitter value of 112 ps, typically for 3.125 Gbps SRIO and XAUI protocols.
- (2) The minimum reconfig_clk frequency is 2.5 MHz if the transceiver channel is configured in **Transmitter Only** mode. The minimum reconfig_clk frequency is 37.5 MHz if the transceiver channel is configured in **Receiver Only** or **Receiver and Transmitter** mode.
- (3) The device cannot tolerate prolonged operation at this absolute maximum.
- (4) The rate matcher supports only up to ±300 parts per million (ppm).
- (5) Supported for the F169 and F324 device packages only.
- (6) Supported for the F484, F672, and F896 device packages only. Pending device characterization.
- (7) To support CDR ppm tolerance greater than ±300 ppm, implement ppm detector in user logic and configure CDR to Manual Lock Mode.
- (8) Asynchronous spread-spectrum clocking is not supported.
- (9) For the EP4CGX30 (F484 package only), EP4CGX50, and EP4CGX75 devices, the CDR ppl tolerance is ±200 ppm.
- (10) Time taken until pll locked goes high after pll powerdown deasserts.
- (11) Time that the CDR must be kept in lock-to-reference mode after rx analogreset deasserts and before rx locktodata is asserted in manual mode.
- (12) Time taken to recover valid data after the rx_locktodata signal is asserted in manual mode (Figure 1–2), or after rx_freqlocked signal goes high in automatic mode (Figure 1–3).
- (13) Time taken to recover valid data after the $rx_locktodata$ signal is asserted in manual mode.
- (14) Time taken to recover valid data after the $rx_freqlocked$ signal goes high in automatic mode.
- (15) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.

Davisa		Performance													
Device	C6	C7	C8	C8L (1)	C9L (1)	17	I8L (1)	A7	Unit						
EP4CE55	500	437.5	402	362	265	437.5	362	_	MHz						
EP4CE75	500	437.5	402	362	265	437.5	362	_	MHz						
EP4CE115	_	437.5	402	362	265	437.5	362	_	MHz						
EP4CGX15	500	437.5	402	_	_	437.5	_	_	MHz						
EP4CGX22	500	437.5	402	_	_	437.5	_	_	MHz						
EP4CGX30	500	437.5	402	_	_	437.5	_	_	MHz						
EP4CGX50	500	437.5	402	_	_	437.5	_	_	MHz						
EP4CGX75	500	437.5	402	_	_	437.5	_	_	MHz						
EP4CGX110	500	437.5	402	_	_	437.5	_	_	MHz						
EP4CGX150	500	437.5	402	_	_	437.5	_	_	MHz						

Note to Table 1-24:

PLL Specifications

Table 1–25 lists the PLL specifications for Cyclone IV devices when operating in the commercial junction temperature range (0°C to 85°C), the industrial junction temperature range (-40°C to 100°C), the extended industrial junction temperature range (-40°C to 125°C), and the automotive junction temperature range (-40°C to 125°C). For more information about the PLL block, refer to "Glossary" on page 1–37.

Table 1–25. PLL Specifications for Cyclone IV Devices (1), (2) (Part 1 of 2)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (-6, -7, -8 speed grades)	5	_	472.5	MHz
f _{IN} (3)	Input clock frequency (-8L speed grade)	5	_	362	MHz
	Input clock frequency (-9L speed grade)	5	_	265	MHz
f _{INPFD}	PFD input frequency	5	_	325	MHz
f _{VCO} (4)	PLL internal VCO operating range	600	_	1300	MHz
f _{INDUTY}	Input clock duty cycle	40	_	60	%
t _{INJITTER_CCJ} (5)	Input clock cycle-to-cycle jitter F _{REF} ≥ 100 MHz	_	_	0.15	UI
	F _{REF} < 100 MHz	_	_	±750	ps
f _{OUT_EXT} (external clock output) (3)	PLL output frequency	_	_	472.5	MHz
	PLL output frequency (-6 speed grade)	_	_	472.5	MHz
	PLL output frequency (-7 speed grade)	_	_	450	MHz
f _{OUT} (to global clock)	PLL output frequency (-8 speed grade)	_	_	402.5	MHz
	PLL output frequency (-8L speed grade)	_	_	362	MHz
	PLL output frequency (-9L speed grade)	_	_	265	MHz
toutduty	Duty cycle for external clock output (when set to 50%)	45	50	55	%
t _{LOCK}	Time required to lock from end of device configuration	_	_	1	ms

⁽¹⁾ Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades.

For more information about the supported maximum clock rate, device and pin planning, IP implementation, and device termination, refer to Section III: System Performance Specifications of the External Memory Interfaces Handbook.



Actual achievable frequency depends on design- and system-specific factors. Perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

High-Speed I/O Specifications

Table 1–31 through Table 1–36 list the high-speed I/O timing for Cyclone IV devices. For definitions of high-speed timing specifications, refer to "Glossary" on page 1–37.

Table 1–31. RSDS Transmitter Timing Specifications for Cyclone IV Devices (1), (2), (4) (Part 1 of 2)

			C6			C7, I	7		C8, A	7		C8L, I	BL		C9L		
Symbol	Modes	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
	×10	5	_	180	5	_	155.5	5	_	155.5	5		155.5	5	_	132.5	MHz
	×8	5		180	5		155.5	5	_	155.5	5		155.5	5	_	132.5	MHz
f _{HSCLK} (input clock	×7	5		180	5	_	155.5	5	_	155.5	5		155.5	5	_	132.5	MHz
frequency)	×4	5	_	180	5	_	155.5	5	_	155.5	5	_	155.5	5	_	132.5	MHz
1 37	×2	5	_	180	5		155.5	5	_	155.5	5		155.5	5	_	132.5	MHz
	×1	5		360	5	_	311	5	_	311	5		311	5	_	265	MHz
	×10	100	_	360	100		311	100	_	311	100		311	100	_	265	Mbps
	×8	80	_	360	80		311	80	_	311	80		311	80	_	265	Mbps
Device operation in	×7	70	_	360	70	_	311	70		311	70	_	311	70	_	265	Mbps
Mbps	×4	40	_	360	40		311	40	_	311	40		311	40	_	265	Mbps
'	×2	20	_	360	20		311	20	_	311	20		311	20	_	265	Mbps
	×1	10	_	360	10	_	311	10		311	10	_	311	10	_	265	Mbps
t _{DUTY}	_	45	_	55	45		55	45	_	55	45		55	45	_	55	%
Transmitter channel-to- channel skew (TCCS)	_	_	_	200	_	_	200	_	_	200	_	_	200	_	_	200	ps
Output jitter (peak to peak)	_	_	_	500	_	_	500	_	_	550	_	_	600	_	_	700	ps
t _{RISE}	$20 - 80\%$, $C_{LOAD} = 5 pF$	_	500	_	_	500	_	_	500	_	_	500	—	_	500	_	ps
t _{FALL}	20 – 80%, C _{LOAD} = 5 pF	_	500	_	_	500	1		500	_	_	500	ı	_	500		ps

Table 1–31. RSDS Transmitter Timing Specifications for Cyclone IV Devices (1), (2), (4) (Part 2 of 2)

Cumbol	Modes		C6			C7, I	7		C8, A	7		C8L, I	BL		C9L		llnit
Symbol		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
t _{LOCK} (3)	_	_		1	_	_	1	_		1	_	_	1	_		1	ms

Notes to Table 1-31:

- (1) Applicable for true RSDS and emulated RSDS_E_3R transmitter.
- (2) Cyclone IV E devices—true RSDS transmitter is only supported at the output pin of Row I/O Banks 1, 2, 5, and 6. Emulated RSDS transmitter is supported at the output pin of all I/O Banks.

 Cyclone IV GX devices—true RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.
- (3) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.
- (4) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

Table 1–32. Emulated RSDS_E_1R Transmitter Timing Specifications for Cyclone IV Devices (1), (3) (Part 1 of 2)

Ob.al	Madaa		C6			C7, 17	'		C8, A7	7	(C8L, 18	BL		C9L		11!4
Symbol	Modes	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
	×10	5	_	85	5		85	5		85	5		85	5	_	72.5	MHz
	×8	5	_	85	5	_	85	5	_	85	5		85	5	_	72.5	MHz
f _{HSCLK} (input clock	×7	5	_	85	5	_	85	5	_	85	5	_	85	5	_	72.5	MHz
frequency)	×4	5	_	85	5	_	85	5		85	5		85	5	_	72.5	MHz
	×2	5		85	5	_	85	5	_	85	5		85	5	_	72.5	MHz
	×1	5	_	170	5	_	170	5	_	170	5		170	5	_	145	MHz
	×10	100	_	170	100	_	170	100	_	170	100	_	170	100		145	Mbps
	×8	80	_	170	80	_	170	80	_	170	80	_	170	80	_	145	Mbps
Device operation in	×7	70	_	170	70	_	170	70	_	170	70		170	70	_	145	Mbps
Mbps	×4	40	_	170	40		170	40	_	170	40	_	170	40	_	145	Mbps
	×2	20	1	170	20	_	170	20		170	20		170	20		145	Mbps
	×1	10	-	170	10		170	10		170	10		170	10	_	145	Mbps
t _{DUTY}	_	45	_	55	45		55	45	_	55	45	_	55	45	_	55	%
TCCS	_	_	1	200	_	_	200	_		200	_		200	_		200	ps
Output jitter (peak to peak)	_	_		500	_	_	500	_		550	_	_	600	_		700	ps
	20 – 80%,																
t _{RISE}	C _{LOAD} = 5 pF	_	500	_	_	500	_	_	500	_	_	500	_	_	500	_	ps
	20 – 80%,																
t _{FALL}	C _{LOAD} = 5 pF	_	500	_	_	500	_	_	500	_	_	500	_		500	_	ps

Table 1–32. Emulated RSDS_E_1R Transmitter Timing Specifications for Cyclone IV Devices (1), (3) (Part 2 of 2)

	Symbol	Modes		C6			C7, 17	1		C8, A7	7	(C8L, 18	L		C9L		Unit
Symbol	woues	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit	
t_{LOO}	CK <i>(2)</i>	_		_	1	_	_	1	_	_	1	_		1	_	_	1	ms

Notes to Table 1-32:

- (1) Emulated RSDS_E_1R transmitter is supported at the output pin of all I/O Banks of Cyclone IV E devices and I/O Banks 3, 4, 5, 6, 7, 8, and 9 of Cyclone IV GX devices.
- (2) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.
- (3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

Table 1–33. Mini-LVDS Transmitter Timing Specifications for Cyclone IV Devices (1), (2), (4)

0			C6			C7, I	7		C8, A	7		C8L, I	8L		C9L		
Symbol	Modes	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
	×10	5	_	200	5	_	155.5	5	_	155.5	5	_	155.5	5	_	132.5	MHz
	×8	5	_	200	5	_	155.5	5	_	155.5	5	_	155.5	5	_	132.5	MHz
f _{HSCLK} (input clock	×7	5		200	5	_	155.5	5	_	155.5	5		155.5	5	_	132.5	MHz
frequency)	×4	5		200	5		155.5	5		155.5	5		155.5	5		132.5	MHz
1 37	×2	5		200	5	_	155.5	5	_	155.5	5		155.5	5	_	132.5	MHz
	×1	5		400	5		311	5		311	5		311	5		265	MHz
	×10	100		400	100	_	311	100		311	100		311	100	_	265	Mbps
	×8	80		400	80		311	80		311	80		311	80		265	Mbps
Device operation in	×7	70	_	400	70	_	311	70	_	311	70	_	311	70	_	265	Mbps
Mbps	×4	40		400	40	_	311	40		311	40		311	40	_	265	Mbps
•	×2	20		400	20	_	311	20	_	311	20		311	20		265	Mbps
	×1	10	_	400	10	_	311	10	_	311	10	_	311	10	_	265	Mbps
t _{DUTY}	_	45		55	45	_	55	45	_	55	45		55	45	_	55	%
TCCS	_	_	_	200	_	_	200	_	_	200	_	_	200	_	_	200	ps
Output jitter (peak to peak)	_	_	_	500	_	_	500	_	_	550	_	_	600	_	_	700	ps
t _{RISE}	20 – 80%, C _{LOAD} = 5 pF	_	500	_	_	500	_	_	500	_	_	500	_	_	500	_	ps
t _{FALL}	20 – 80%, C _{LOAD} = 5 pF	_	500	_	_	500	_	_	500	_	_	500	_	_	500	_	ps
t _{LOCK} (3)	_	_	_	1	_	_	1	_	_	1	_	_	1	_	_	1	ms

Notes to Table 1-33:

- (1) Applicable for true and emulated mini-LVDS transmitter.
- (2) Cyclone IV E—true mini-LVDS transmitter is only supported at the output pin of Row I/O Banks 1, 2, 5, and 6. Emulated mini-LVDS transmitter is supported at the output pin of all I/O banks.

 Cyclone IV GX—true mini-LVDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated mini-LVDS transmitter is supported at the
 - Cyclone IV GX—true mini-LVDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated mini-LVDS transmitter is supported at the output pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.
- (3) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.
- (4) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

Cumbal	Modes	C	6	C7,	, 17	C8,	A7	C8L,	, I8L	C	9L	Ilmit
Symbol	Modes	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit
t _{DUTY}	_	45	55	45	55	45	55	45	55	45	55	%
TCCS	_	_	200	_	200	_	200	_	200	_	200	ps
Output jitter (peak to peak)	_	_	500	_	500	_	550	_	600	_	700	ps
t _{LOCK} (2)	_	_	1	_	1	_	1	_	1	_	1	ms

Notes to Table 1-35:

- (1) Cyclone IV E—emulated LVDS transmitter is supported at the output pin of all I/O Banks. Cyclone IV GX—emulated LVDS transmitter is supported at the output pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.
- (2) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.
- (3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

Table 1–36. LVDS Receiver Timing Specifications for Cyclone IV Devices (1), (3)

0	80	C	6	C 7,	, 17	C8,	A7	C8L	, I8L	C	9L	1111
Symbol	Modes	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit
	×10	10	437.5	10	370	10	320	10	320	10	250	MHz
	×8	10	437.5	10	370	10	320	10	320	10	250	MHz
f _{HSCLK} (input clock	×7	10	437.5	10	370	10	320	10	320	10	250	MHz
frequency)	×4	10	437.5	10	370	10	320	10	320	10	250	MHz
1 3,	×2	10	437.5	10	370	10	320	10	320	10	250	MHz
	×1	10	437.5	10	402.5	10	402.5	10	362	10	265	MHz
	×10	100	875	100	740	100	640	100	640	100	500	Mbps
	×8	80	875	80	740	80	640	80	640	80	500	Mbps
HSIODR	×7	70	875	70	740	70	640	70	640	70	500	Mbps
חטוטח	×4	40	875	40	740	40	640	40	640	40	500	Mbps
	×2	20	875	20	740	20	640	20	640	20	500	Mbps
	×1	10	437.5	10	402.5	10	402.5	10	362	10	265	Mbps
SW	_	_	400	_	400	_	400	_	550	_	640	ps
Input jitter tolerance	_	_	500	_	500	_	550	_	600	_	700	ps
t _{LOCK} (2)	_	_	1	_	1	_	1		1		1	ms

Notes to Table 1-36:

- Cyclone IV E—LVDS receiver is supported at all I/O Banks.
 Cyclone IV GX—LVDS receiver is supported at I/O Banks 3, 4, 5, 6, 7, 8, and 9.
- (2) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.
- (3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

External Memory Interface Specifications

The external memory interfaces for Cyclone IV devices are auto-calibrating and easy to implement.



For more information about the supported maximum clock rate, device and pin planning, IP implementation, and device termination, refer to *Section III: System Performance Specifications* of the *External Memory Interface Handbook*.

Table 1–37 lists the memory output clock jitter specifications for Cyclone IV devices.

Table 1–37. Memory Output Clock Jitter Specifications for Cyclone IV Devices (1), (2)

Parameter	Symbol	Min	Max	Unit
Clock period jitter	t _{JIT(per)}	-125	125	ps
Cycle-to-cycle period jitter	t _{JIT(cc)}	-200	200	ps
Duty cycle jitter	t _{JIT(duty)}	-150	150	ps

Notes to Table 1-37:

- Memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2 standard.
- (2) The clock jitter specification applies to memory output clock pins generated using DDIO circuits clocked by a PLL output routed on a global clock (GCLK) network.

Duty Cycle Distortion Specifications

Table 1–38 lists the worst case duty cycle distortion for Cyclone IV devices.

Table 1–38. Duty Cycle Distortion on Cyclone IV Devices I/O Pins (1), (2), (3)

Symbol	C	6	C7	, 1 7	C8, I8	BL, A7	C	9L	Unit
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Ullit
Output Duty Cycle	45	55	45	55	45	55	45	55	%

Notes to Table 1-38:

- (1) The duty cycle distortion specification applies to clock outputs from the PLLs, global clock tree, and IOE driving the dedicated and general purpose I/O pins.
- (2) Cyclone IV devices meet the specified duty cycle distortion at the maximum output toggle rate for each combination of I/O standard and current strength.
- (3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

OCT Calibration Timing Specification

Table 1–39 lists the duration of calibration for series OCT with calibration at device power-up for Cyclone IV devices.

Table 1–39. Timing Specification for Series OCT with Calibration at Device Power-Up for Cyclone IV Devices $^{(1)}$

Symbol	Description	Maximum	Units	
t _{OCTCAL}	Duration of series OCT with calibration at device power-up	20	μs	

Note to Table 1-39:

(1) OCT calibration takes place after device configuration and before entering user mode.

IOE Programmable Delay

Table 1–40 and Table 1–41 list the IOE programmable delay for Cyclone IV E 1.0 V core voltage devices.

Table 1–40. IOE Programmable Delay on Column Pins for Cyclone IV E 1.0 V Core Voltage Devices (1), (2)

		Number		Max Offset					
Parameter	Paths Affected	of	Min Offset	Fast Corner		Slow Corner			Unit
		Setting		C8L	I8L	C8L	C9L	I8L	
Input delay from pin to internal cells	Pad to I/O dataout to core	7	0	2.054	1.924	3.387	4.017	3.411	ns
Input delay from pin to input register	Pad to I/O input register	8	0	2.010	1.875	3.341	4.252	3.367	ns
Delay from output register to output pin	I/O output register to pad	2	0	0.641	0.631	1.111	1.377	1.124	ns
Input delay from dual-purpose clock pin to fan-out destinations	Pad to global clock network	12	0	0.971	0.931	1.684	2.298	1.684	ns

Notes to Table 1-40:

- (1) The incremental values for the settings are generally linear. For the exact values for each setting, use the latest version of the Quartus II software.
- (2) The minimum and maximum offset timing numbers are in reference to setting **0** as available in the Quartus II software.

Table 1–41. IOE Programmable Delay on Row Pins for Cyclone IV E 1.0 V Core Voltage Devices (1), (2)

		Number			ı	Vax Offse	t		
Parameter	Paths Affected	of	Min Offset	Fast Corner		Slow Corner			Unit
		Setting		C8L	I8L	C8L	C9L	I8L	
Input delay from pin to internal cells	Pad to I/O dataout to core	7	0	2.057	1.921	3.389	4.146	3.412	ns
Input delay from pin to input register	Pad to I/O input register	8	0	2.059	1.919	3.420	4.374	3.441	ns
Delay from output register to output pin	I/O output register to pad	2	0	0.670	0.623	1.160	1.420	1.168	ns
Input delay from dual-purpose clock pin to fan-out destinations	Pad to global clock network	12	0	0.960	0.919	1.656	2.258	1.656	ns

Notes to Table 1-41:

- (1) The incremental values for the settings are generally linear. For the exact values for each setting, use the latest version of the Quartus II software.
- (2) The minimum and maximum offset timing numbers are in reference to setting $\bf 0$ as available in the Quartus II software.

I/O Timing

Use the following methods to determine I/O timing:

- the Excel-based I/O Timing
- the Quartus II timing analyzer

The Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get a timing budget estimation as part of the link timing analysis. The Quartus II timing analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after place-and-route is complete.

The Excel-based I/O Timing spreadsheet is downloadable from Cyclone IV Devices Literature website.

Glossary

Table 1–46 lists the glossary for this chapter.

Table 1-46. Glossary (Part 1 of 5)

Letter	Term	Definitions					
Α	_	-					
В	_	_					
С	_	_					
D	_	_					
E	_	_					
F	f _{HSCLK}	High-speed I/O block: High-speed receiver/transmitter input and output clock frequency.					
G	GCLK	Input pin directly to Global Clock network.					
u	GCLK PLL	Input pin to Global Clock network through the PLL.					
Н	HSIODR	High-speed I/O block: Maximum/minimum LVDS data transfer rate (HSIODR = 1/TUI).					
ı	Input Waveforms for the SSTL Differential I/O Standard	V _{IH} V _{REF} V _{IL}					

Table 1-46. Glossary (Part 3 of 5)

Letter	Term	Definitions							
	R_L	Receiver differential input discrete resistor (external to Cyclone IV devices).							
		Receiver input waveform for LVDS and LVPECL differential standards: Single-Ended Waveform							
		Positive Channel (p) = V _{IH}							
		Negative Channel (n) = V _{IL}							
R	Receiver Input Waveform	Ground							
		Differential Waveform (Mathematical Function of Positive & Negative Channel)							
		V _{ID} 0 V							
		V _{ID} p-n							
	Receiver input skew margin (RSKM)	High-speed I/O block: The total margin left after accounting for the sampling window and TCCS. RSKM = (TUI – SW – TCCS) / 2.							
		V _{CGIO}							
		V _{IH(DC)}							
		V_{REF} $V_{IL(DC)}$							
	Single-ended voltage-	Vil(AC)							
S	referenced I/O Standard	$\overline{V_{ ext{OL}}}$							
		The JEDEC standard for SSTI and HSTL I/O standards defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input crosses the AC value, the receiver changes to the new logic state. The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform <i>ringing</i> .							
	SW (Sampling Window)	High-speed I/O block: The period of time during which the data must be valid to capture it correctly. The setup and hold times determine the ideal strobe position in the sampling window							

Table 1-46. Glossary (Part 5 of 5)

Letter	Term	Definitions
	V _{CM(DC)}	DC common mode input voltage.
	V _{DIF(AC)}	AC differential input voltage: The minimum AC input differential voltage required for switching.
	V _{DIF(DC)}	DC differential input voltage: The minimum DC input differential voltage required for switching.
	V _{ICM}	Input common mode voltage: The common mode of the differential signal at the receiver.
	V _{ID}	Input differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	V _{IH}	Voltage input high: The minimum positive voltage applied to the input that is accepted by the device as a logic high.
	V _{IH(AC)}	High-level AC input voltage.
	V _{IH(DC)}	High-level DC input voltage.
	V _{IL}	Voltage input low: The maximum positive voltage applied to the input that is accepted by the device as a logic low.
	V _{IL (AC)}	Low-level AC input voltage.
	V _{IL (DC)}	Low-level DC input voltage.
	V _{IN}	DC input voltage.
	V _{OCM}	Output common mode voltage: The common mode of the differential signal at the transmitter.
v	V _{OD}	Output differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter. $V_{OD} = V_{OH} - V_{OL}$.
	V _{OH}	Voltage output high: The maximum positive voltage from an output that the device considers is accepted as the minimum positive high level.
	V _{OL}	Voltage output low: The maximum positive voltage from an output that the device considers is accepted as the maximum positive low level.
	V _{OS}	Output offset voltage: $V_{OS} = (V_{OH} + V_{OL}) / 2$.
	V _{OX (AC)}	AC differential output cross point voltage: the voltage at which the differential output signals must cross.
	V_{REF}	Reference voltage for the SSTL and HSTL I/O standards.
	V _{REF (AC)}	AC input reference voltage for the SSTL and HSTL I/O standards. $V_{REF(AC)} = V_{REF(DC)} + noise$. The peak-to-peak AC noise on V_{REF} must not exceed 2% of $V_{REF(DC)}$.
	V _{REF (DC)}	DC input reference voltage for the SSTL and HSTL I/O standards.
	V _{SWING (AC)}	AC differential input voltage: AC input differential voltage required for switching. For the SSTL differential I/O standard, refer to Input Waveforms.
	V _{SWING (DC)}	DC differential input voltage: DC input differential voltage required for switching. For the SSTL differential I/O standard, refer to Input Waveforms.
	V _{TT}	Termination voltage for the SSTL and HSTL I/O standards.
	V _{X (AC)}	AC differential input cross point voltage: The voltage at which the differential input signals must cross.
W	_	
X	_	_
Υ	_	_
Z		_

Document Revision History

Table 1–47 lists the revision history for this chapter.

Table 1–47. Document Revision History

Date	Version	Changes				
March 2016	2.0	Updated note (5) in Table 1–21 to remove support for the N148 package.				
October 2014	1.0	Updated maximum value for V _{CCD_PLL} in Table 1–1.				
October 2014 1.9		Removed extended temperature note in Table 1–3.				
December 2013	1.8	Updated Table 1–21 by adding Note (15).				
May 2013	1.7	Updated Table 1–15 by adding Note (4).				
		■ Updated the maximum value for V _I , V _{CCD_PLL} , V _{CCIO} , V _{CC_CLKIN} , V _{CCH_GXB} , and V _{CCA_GXB} Table 1–1.				
		■ Updated Table 1–11 and Table 1–22.				
October 2012	1.6	 Updated Table 1–21 to include peak-to-peak differential input voltage for the Cyclone IV GX transceiver input reference clock. 				
		■ Updated Table 1–29 to include the typical DCLK value.				
		■ Updated the minimum f _{HSCLK} value in Table 1–31, Table 1–32, Table 1–33, Table 1–34, and Table 1–35.				
	er 2011 1.5	 Updated "Maximum Allowed Overshoot or Undershoot Voltage", "Operating Conditions", and "PLL Specifications" sections. 				
November 2011		■ Updated Table 1–2, Table 1–3, Table 1–4, Table 1–5, Table 1–8, Table 1–9, Table 1–15, Table 1–18, Table 1–19, and Table 1–21.				
		■ Updated Figure 1–1.				
		■ Updated for the Quartus II software version 10.1 release.				
December 2010	1.4	■ Updated Table 1–21 and Table 1–25.				
		■ Minor text edits.				
		Updated for the Quartus II software version 10.0 release:				
		■ Updated Table 1–3, Table 1–4, Table 1–21, Table 1–25, Table 1–28, Table 1–30, Table 1–40, Table 1–41, Table 1–42, Table 1–43, Table 1–44, and Table 1–45.				
July 2010	1.3	■ Updated Figure 1–2 and Figure 1–3.				
		 Removed SW Requirement and TCCS for Cyclone IV Devices tables. 				
		■ Minor text edits.				
		Updated to include automotive devices:				
		Updated the "Operating Conditions" and "PLL Specifications" sections.				
March 2010	1.2	■ Updated Table 1–1, Table 1–8, Table 1–9, Table 1–21, Table 1–26, Table 1–27, Table 1–31, Table 1–32, Table 1–33, Table 1–35, Table 1–36, Table 1–37, Table 1–38, Table 1–40, Table 1–42, and Table 1–43.				
		■ Added Table 1–5 to include ESD for Cyclone IV devices GPIOs and HSSI I/Os.				
		 Added Table 1–44 and Table 1–45 to include IOE programmable delay for Cyclone IV E 1.2 V core voltage devices. 				
		Minor text edits.				